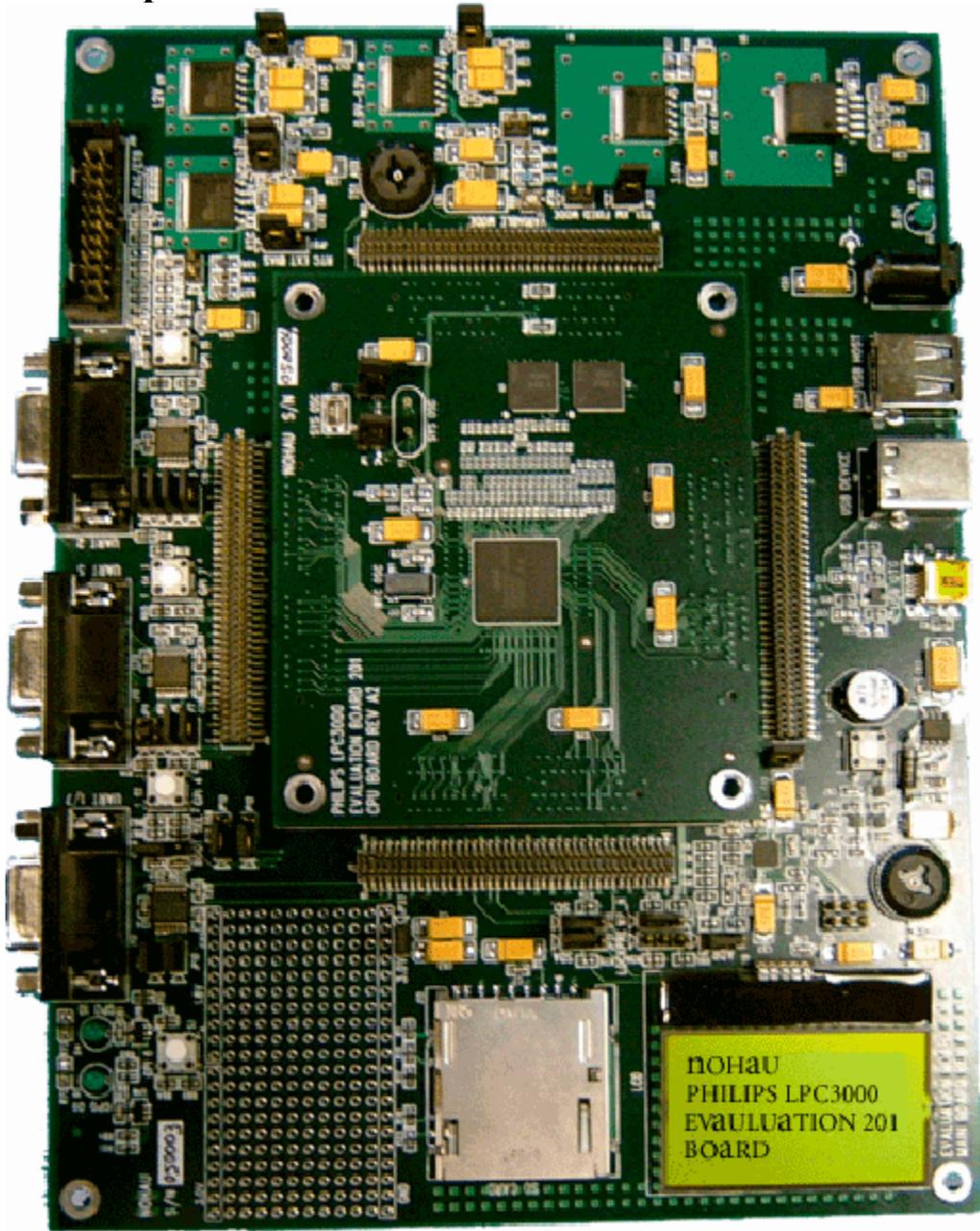


Philips NXP LPC3000 Evaluation Board Users Manual



Revision History

Revision	Date	Author	Comments
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1. Introduction

This document details the setup and configuration of the NXP LPC3000 evaluation board 201 (hereafter referred to as the EVB).

The EVB is intended to provide a mechanism for easy customer evaluation of the NXP LPC3000 microcontroller and to facilitate hardware and software development.

1.1 EVB Feature List

The EVB provides the following features:

- A Single power supply input (5.0V), regulated on board to provide all the necessary EVB voltages.
- User Reset pushbutton switch.
- 20 Way JTAG/ETB connector.
- 32M (8M x 32) Bytes of SDRAM.
- 32M (32M x 8) Bytes of NAND FLASH.
- 1 - LCD Module with NXP PCF8558 built in.
- 1 - SD Card connector.
- 3 - USB connectors (USB A Receptacle Connector for USB Host; USB B Receptacle Connector for USB Device; USB Mini AB Receptacle Connector for USB OTG) with NXP ISP1301.
- 3 - UART (RS232) physical interface circuits connected to standard PC style DB9 female connectors.
- 4 - 80 pin break-out headers, to provide easy access to many of the microcontroller pins.
- 4 - User input pushbutton switches.
- 2 - User output LEDs.
- Small prototyping area consisting of an area of 0.1 inch spaced through holes with easy access to ground and 3.0V, 1.8V power supply points.

IMPORTANT

Before you apply power to the EVB, please **fully read** the following sections on how to correctly configure the board. However, the boards **default** configuration **should not** require any change in configuration before you power on the EVB.

A Failure in configuration of the board may cause device or EVB damage.

2. EVB Configuration

This section details the configuration of each of the EVB functional blocks.

Throughout this document, all default jumper settings are clearly marked with “(D)” and are shown in **blue** text. This should allow a more rapid return to the default state of the EVB if required. Note that **all** 3 pin jumpers have the default configuration with a jumper header fitted to pins 1-2 except JP28.

The main EVB functional blocks are shown below to help with quick location of jumpers etc. The EVB has been designed to try and make it as easy as possible to use. The PCB has detailed silkscreen legend and, where possible, have been segmented into functional blocks.

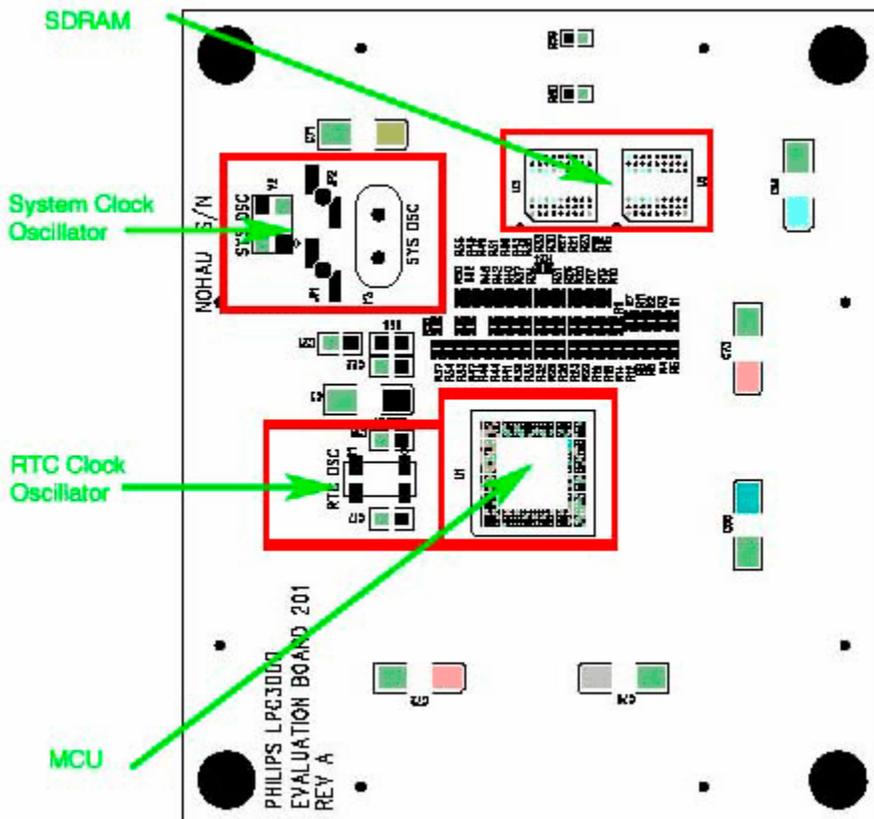


Figure 2-1 EVB (CPU Board) Functional Blocks

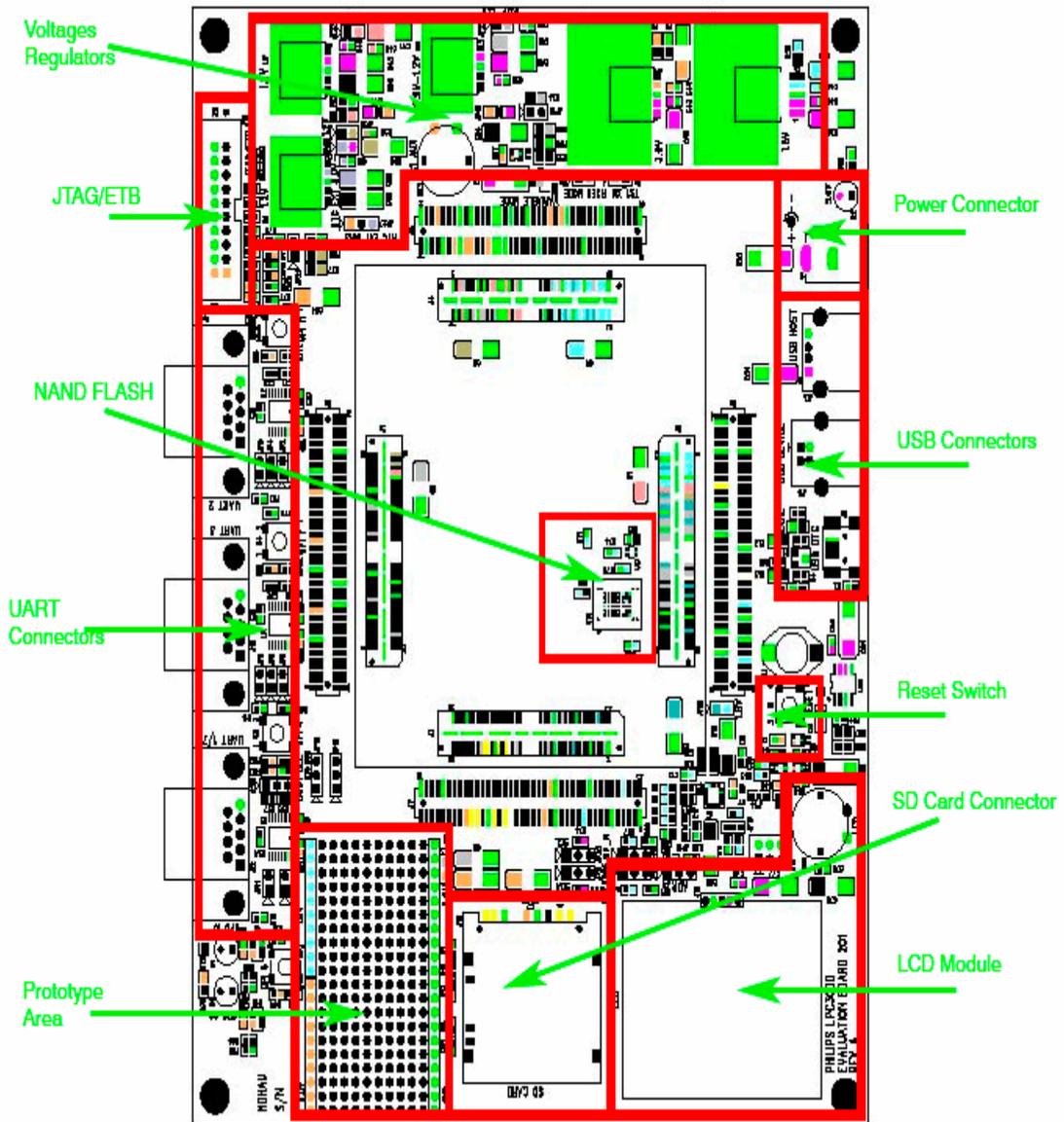


Figure 2-2 EVB (Main Board) Functional Blocks

2.1 System/RTC Oscillator Selection

2.1.1 System Oscillator Selection Jumpers (JP1, JP2)

[Appendix figure 1](#)

The EVB supports 2 possible MCU system clock oscillator sources:

- (1) An on board system clock oscillator Y2 (13MHz).
- (2) A socket Y3 for user system clock oscillator.

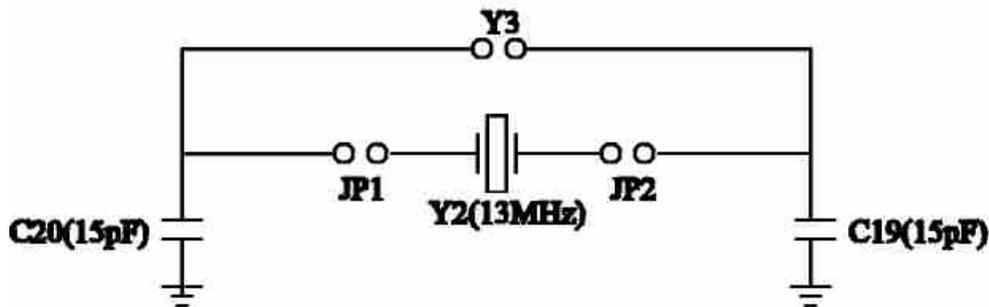


Figure 2-3 System Oscillator Selection

The selection between these options is controlled using jumpers (JP1, JP2) as shown below:

Table 2-1 System Oscillator Selection Jumpers

Jumper	PCB Legend	Position	Description
JP1		FITTED (D)	Connects the on board system clock oscillator Y2.
		REMOVED	Disconnects the on board system clock oscillator. Connects the user system clock oscillator Y3.
JP2		FITTED (D)	Connects the on board system clock oscillator Y2.
		REMOVED	Disconnects the on board system clock oscillator. Connects the user system clock oscillator Y3.

2.1.2 RTC Oscillator

[Appendix Figure 1](#)

The EVB has a MCU RTC clock oscillator.

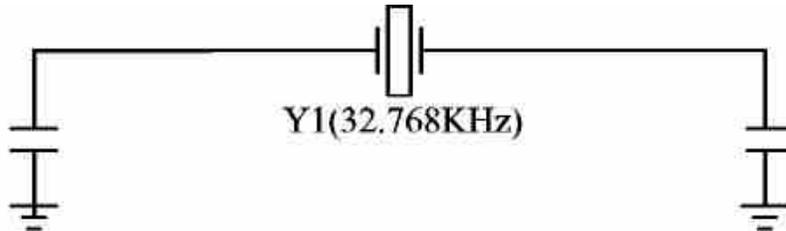


Figure 2-4 RTC Oscillator

2.2 Power Supply Configuration

The EVB requires an external supply voltage of 5V DC, minimum 3Amp.

2.2.1 Power Supply Input Connector (J17)

[Appendix Figure 2](#)

This connector provides a convenient hook-up mechanism for a fabricated power lead such as those found on wall-plug DC adapters. Care must be taken to ensure the 2.0mm plug uses the correct polarization as shown below:



Figure 2-5 2.0mm Power Connector

2.2.2 Power Supply Configuration Jumpers

The EVB has 6 voltage regulators on board:

- 1.8V voltage regulator (U5) to supply the MCU 1.8V voltages (VDDio18, VDDsdram18) and the EVB peripherals 1.8V voltages.

[Appendix Figure 2](#)

Table 2-2 1.8V Voltage Regulator Configuration Jumper

Jumper	PCB Legend	Position	Description
JP22	1.8V	FITTED (D) REMOVED	Connects the MCU 1.8V voltages and the EVB peripherals 1.8V voltages. Allows multimeter to measure the current drawn by the MCU 1.8V voltages.

- 3.0V voltage regulator (U6) to supply the MCU 3.0V voltages (VDDio28, VDDio1828, VDD1828, VDDad28, VDD28) and the EVB peripherals 3.0V voltages.

[Appendix Figure 2](#)

Table 2-3 3.0V Voltage Regulator Configuration Jumper

Jumper	PCB Legend	Position	Description
JP23	3.0V	FITTED (D) REMOVED	Connects the MCU 3.0V voltages and the EVB peripherals 3.0V voltages. Allows multimeter to measure the current drawn by the MCU 3.0V voltages.

- 1.2V voltage regulator (U7) to supply the MCU 1.2V voltages (VDD12, VDDosc12, VDDpll12, VDDcorefixed12).

[Appendix Figure 2](#)

Table 2-4 1.2V Voltage Regulator Configuration Jumper

Jumper	PCB Legend	Position	Description
JP24	1.2V	FITTED (D) REMOVED	Connects the MCU 1.2V voltages. Allows multimeter to measure the current drawn by the MCU 1.2V voltages.

- 0.9V~1.2V core voltage regulator (U8) to supply the MCU 0.9V~1.2V Core voltages (VDDcore12).

[Appendix Figure 2](#)

Table 2-5 0.9V~1.2V Core Voltage Regulator Configuration Jumpers

Jumper	PCB Legend	Position	Description
JP25	0.9V~1.2V	FITTED (D) REMOVED	Connects the MCU 0.9V~1.2V Core voltages. Allows multimeter to measure the current drawn by the MCU 0.9V~1.2V Core voltages.
JP19		REMOVED (D) FITTED	0.9V~1.2V core voltage regulator output is set by the signal HIGHCORE. 1.2V for HIGHCORE = LOW; 0.9V for HIGHCORE = HIGH. 0.9V~1.2V core voltage regulator output is set to 0.9V.
JP34	FIXED MODE	REMOVED (D) FITTED	1.2V (for HIGHCORE = LOW) is configured as 1.17V~1.31V variable mode controlled by the potentiometer R89. 1.2V (for HIGHCORE = LOW) is configured as 1.17V fixed mode.

- 1.2V RTC voltage regulator (U9) to supply the MCU 1.2V RTC voltages (VDDrtc12, VDDrtcosc12, VDDrtccore).

[Appendix Figure 2](#)

Table 2-6 1.2V RTC Voltage Regulator Configuration Jumpers

Jumper	PCB Legend	Position	Description
JP26	1.2V	FITTED (D) REMOVED	Connects the MCU 1.2V RTC voltages. Allows multimeter to measure the current drawn by the MCU 1.2V RTC voltages.
JP21		REMOVED (D) FITTED	1.2V RTC voltage regulator output is set to 1.2V. 1.2V RTC voltage regulator output is set to 0.9V.
JP20	RTC EXT 5.0V	FITTED (D) REMOVED	1.2V RTC voltage regulator input is connected to the power supply input connector J17. 1.2V RTC voltage regulator input is disconnected from the power supply input connector J17. 1.2V RTC voltage regulator input can then be connected to external 5.0V power supply through the pin 1 of JP20.
JP27	RTC EXT BIAS	1-2 (D) 2-3	When JP20 is fitted. When JP20 is removed.

2.2.3 LCD Voltage Regulator (U20)

- 3.3V LCD voltage regulator (U20) to supply the LCD voltage.

2.2.3.1 LCD Contrast Adjustment (R86)

- The Contrast Adjustment for the LCD is controlled by the potentiometer R86.

2.2.4 Power Status LED (D2)

When power is applied to the EVB, the green Power Status LED (D2) adjacent to the Power Supply Input Connector (J17) shows the presence of the 5.0V supply voltage.

[Appendix Figure 2](#)

2.3 JTAG/ETB Connector (J18)

[Appendix Figure 3](#)

The JTAG/ETB connector (J18) on the edge of the EVB supports the 20-pin debug interface connector.

About ETB (Embedded Trace Buffer)

As process speeds increase it is increasingly difficult to obtain trace information off a chip from the Embedded Trace Macrocell (ETM). This causes difficulties in maintaining acceptable signal quality or the signals need to be demultiplexed on to what can become a very large number of trace port pins.

The solution is to provide a buffer area on-chip where the trace information is stored, and read from the chip latter, at a slower rate.

The ETB stores data produced by the ETM. The buffered data can then be accessed by the debugging tools using a JTAG (IEEE 1149.1) interface, as shown in figure 2-6.

**** Important ****

When connecting or removing the JTAG/ETB debug interface, power **must be removed from **both** the **EVB** and the **JTAG/ETB debug interface**.**

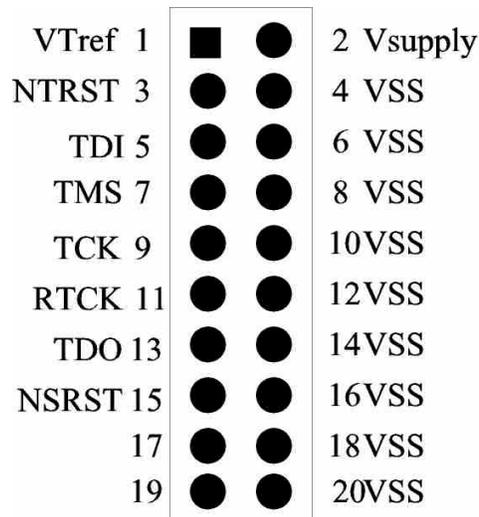


Figure 2-6 JTAG/ETB Connector

2.4 Reset Switch (S1)

[Appendix Figure 3](#)

An active low, push button RESET switch (S1) with a MAXIM MAX823REXK-T device is provided on the EVB. When the 3.0V voltage regulator drops below a certain threshold level (2.63V), the MAXIM MAX823REXK-T device will automatically assert the MCU reset line in order to prevent incorrect operation of the MCU or EVB circuitry. The MAXIM MAX823REXK-T device also provides a de-bounced input for the active low, push button RESET switch (S1). As the JTAG hardware debug probe has the ability to assert the MCU reset line, additional open-drain output buffering scheme is created as shown in Figure 2-7.

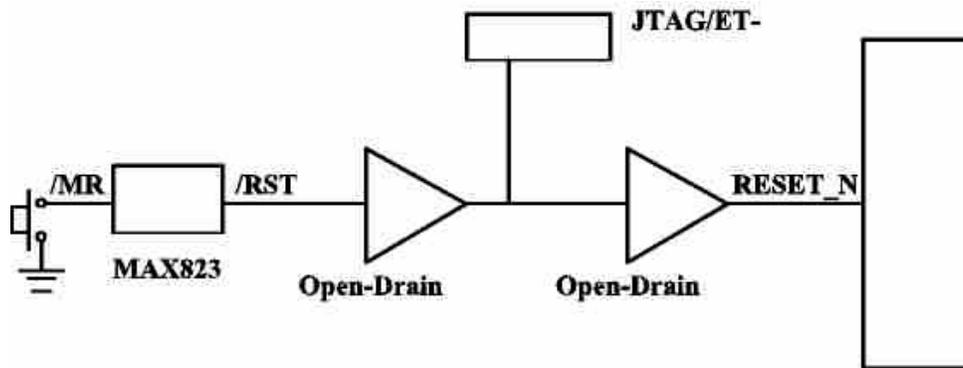


Figure 2-7 Reset buffering Scheme

2.5 Boot Select Input Configuration Jumper (JP32)

[Appendix Figure 3](#)

The Boot Select Input, GPI_01 (SERVICE_N) is configured by the jumper (JP32).

Table 2-7 Boot Select Input Configuration Jumper

Jumper	PCB Legend	Position	Description
JP32	BOOT SEL	1-2 (D) 2-3	GPI_01(SERVICE_N) is set to HIGH to run code from NAND FLASH. GPI_01(SERVICE_N) is set to LOW to download code from UART 5 (J10).

2.6 RS232 Configuration

The EVB has three MAXIM MAX3232ECAE RS232 transceiver devices, providing RS232 signal translation for the MCU. Each of the MAXIM MAX3232ECAE devices has a 9 way female D-Type connector associated. Each of the MCU signals to the RS232 transceiver is jumpered to allow individual isolation if required.

2.6.1 UART 2 Configuration Jumpers (JP2, JP3, JP4, JP5)

[Appendix Figure 3](#)

For the UART 2, the MAXIM MAX3232ECAE device (U2) has a 9 way female D-Type connector (J11) associated.

Table 2-8 UART 2 Configuration Jumpers

Jumper	PCB Legend	Position	Description
JP2		FITTED (D)	Connects U2_TX to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U2_TX from MAXIM MAX3232ECAE device.
JP3		FITTED (D)	Connects U2_RX to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U2_RX from MAXIM MAX3232ECAE device.
JP4		FITTED (D)	Connects U2_HRTS to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U2_HRTS from MAXIM MAX3232ECAE device.
JP5		FITTED (D)	Connects U2_HCTS to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U2_HCTS from MAXIM MAX3232ECAE device.

2.6.2 UART 1/7 Configuration Jumpers (JP12, JP13, JP10, JP11)

[Appendix Figure 3](#)

For the UART 1/7, the MAXIM MAX3232ECAE device (U3) has a 9 way female D-Type connector (J12) associated.

Table 2-9 UART 1/7 Configuration Jumpers

Jumper	PCB Legend	Position	Description
JP12		1-2 (D)	Connects U7_TX to MAXIM MAX3232ECAE device.
		2-3	Connects U1_TX to MAXIM MAX3232ECAE device.
JP13		1-2 (D)	Connects U7_RX to MAXIM MAX3232ECAE device.
		2-3	Connects U1_RX to MAXIM MAX3232ECAE device.
JP10		FITTED (D)	Connects U7_HRTS to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U7_HRTS from MAXIM MAX3232ECAE device.
JP11		FITTED (D)	Connects U7_HCTS to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U7_HCTS from MAXIM MAX3232ECAE device.

2.6.3 UART 5 Configuration Jumpers (JP6, JP7, JP8, JP9)

[Appendix Figure 3](#)

For the UART 5, the MAXIM MAX3232ECAE device (U4) has a 9 way female D-Type connector (J10) associated.

Table 2-10 UART 5 Configuration Jumpers

Jumper	PCB Legend	Position	Description
JP6		FITTED (D)	Connects U5_TX to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U5_TX from MAXIM MAX3232ECAE device.
JP7		FITTED (D)	Connects U5_RX to MAXIM MAX3232ECAE device.
		REMOVED	Disconnects U5_RX from MAXIM MAX3232ECAE device.
JP8		REMOVED (D)	Not in use.
JP9		REMOVED (D)	Not in use.

2.7 SD Card Connector (J15)

[Appendix Figure 3](#)

The EVB supports SD Card with a SD Card connector.
The Detect switch of the SD Card connector is connected to the GPI_5 pin of the MCU.
The output of the Detect switch is LOW when the SD Card is inserted.

2.8 USB Connectors (J9, J13, J14)

[Appendix Figure 3](#)

The EVB has 3 x USB connectors with a Universal Serial Bus (USB) On-The-Go (OTG) transceiver device, NXP ISP1301.

- USB A Receptacle Connector for USB Host (J13).
- USB B Receptacle Connector for USB Device (J14).
- USB Mini AB Receptacle Connector for USB OTG (J9).

2.8.1 I2C Bus Address Configuration Jumpers (JP1)

[Appendix Figure 3](#)

The least least-significant I2C-bus address bit of the NXP ISP1301 is configured by the jumper JP1.

Table 2-11 I2C Bus Address Configuration Jumper

Jumper	PCB Legend	Position	Description
JP1	ADR	1-2 (D) 2-3	The I2C-bus address for the NXP ISP1301 is 0101101 (0x2D). The I2C-bus address for the NXP ISP1301 is 0101100 (0x2C).

2.9 LCD Module (J19)

[Appendix Figure 3](#)

The EVB has a LCD module with NXP PCF8558 built in.

2.9.1 I2C Bus Configuration Jumpers (JP30, JP31)

[Appendix Figure 3](#)

The I2C bus of the LCD module is configured by the jumpers (JP30, JP31).

Table 2-12 I2C Bus Configuration Jumpers

Jumper	PCB Legend	Position	Description
JP30	SCL	1-2 (D) 2-3	Connects I2C1_SCL. Connects I2C2_SCL.
JP31	SDA	1-2 (D) 2-3	Connects I2C1_SDA. Connects I2C2_SDA.

2.9.2 Contrast Adjustment (R86)

[Appendix Figure 3](#)

The Contrast Adjustment of the LCD module is controlled by the potentiometer R86.

2.10 NAND FLASH Chip Select

The on-board NAND FLASH chip select is re-created as shown in Figure 2-8.

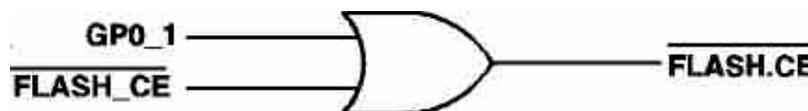


Figure 2-8 NAND FLASH Chip Select

The SRAM chip select available at the break-out header, is re-created as shown in Figure 2-9.

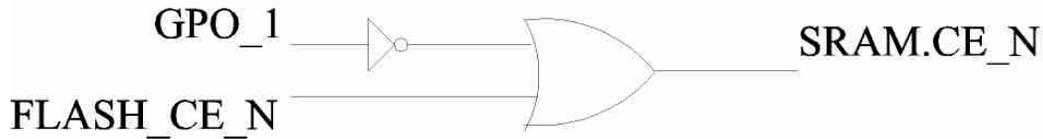


Figure 2-9 SRAM Chip Select

The normal state of the signal GPO_1 is low after reset from the microcontroller. This means that the Flash Chip Enable signal will be active. Since there is no actual enable for Static RAM from the micro we have added a signal (SRAM_CE), that the user can enable by setting the GPO_1 signal to a high state to enable access to Static RAM.

2.11 NAND FLASH Configuration Jumpers

2.11.1 NAND FLASH Write Protect Input Configuration Jumper (JP29)

[Appendix Figure 4](#)

Table 2-13 NAND FLASH Write Protect Input Configuration Jumper

Jumper	PCB Legend	Position	Description
JP29	WP_N	1-2 (D) 2-3	Accepts program or erase operations. Does not accept any program or erase operations.

2.11.2 NAND FLASH Lock Mechanism & Power-On Auto-Read Configuration Jumper (JP28)

[Appendix Figure 4](#)

The table below shows the configuration of the Jumper (JP28) if ST NAND256R3A2AZA6E is installed on the board.

Table 2-14 NAND FLASH Lock Mechanism & Power-On Auto-Read Configuration Jumper (JP28)

Jumper	PCB Legend	Position	Description
JP28	LOCKPRE	REMOVED (D)	Not using LOCK MECHANISM & POWER-ON AUTO-READ is not supported.

The table below shows the configuration of the Jumper (JP28) if SAMSUNG K9F5608Q0C-GIB0 is installed on the board.

Table 2-15 NAND FLASH Lock Mechanism & Power-On Auto-Read Configuration Jumper (JP28)

Jumper	PCB Legend	Position	Description
JP28	LOCKPRE	2-3 (D)	LOCK MECHANISM & POWER-ON AUTO-READ disabled.
		1-2	LOCK MECHANISM & POWER-ON AUTO-READ enabled.

2.12 ADC Configuration Jumper

2.12.1 ADC Configuration Jumper (JP33)

[Appendix Figure 4](#)

Table 2-16 ADC Configuration Jumper

Jumper	PCB Legend	Position	Description
JP33	ADIN1	FITTED (D)	Connects ADIN1 to 0.9V~1.2V Core voltage.
		REMOVED	Disconnects ADIN1 to 0.9V~1.2V Core Voltage.

2.12.2 Potentiometer (R83)

[Appendix Figure 4](#)

ADIN2 is connected to the 3.0V voltage through the potentiometer R83.

2.13 User Input Push Button Switches

2.13.1 User Input Push Button Switch (S2)

[Appendix Figure 4](#)

An active low, push button switch (S2) is connected to GPI_4.

2.13.2 User Input Push Button Switch (S3)

[Appendix Figure 4](#)

An active low, push button switch (S3) is connected to GPI_6.

2.13.3 User Input Push Button Switch (S4)

[Appendix Figure 4](#)

An active low, push button switch (S3) is connected to GPI_7.

2.13.4 User Input Push Button Switch (S5)

[Appendix Figure 4](#)

An active low, push button switch (S5) is connected to GPI_11.

2.14 User Output LEDs

2.14.1 User Output LED (D3)

[Appendix Figure 5](#)

LED (D3) is driven by GPO_9.

2.14.2 User Output LED (D4)

[Appendix Figure 5](#)

LED (D4) is driven by GPO_10.

3. Default Jumpers Summary Table

3.1 EVB (CPU Board) Default Jumpers Summary Table

Table 2-17 EVB (CPU Board) Default Jumpers Summary Table

Jumper	PCB Legend	Position	Description
JP1		FITTED (D)	Connects the on board system clock oscillator Y2.
JP2		FITTED (D)	Connects the on board system clock oscillator Y2.

3.2 EVB (Main Board) Default Jumpers Summary Table

Table 2-18 EVB (Main Board) Default Jumpers Summary Table

Jumper	PCB Legend	Position	Description
JP22	1.8V	FITTED (D)	Connects the MCU 1.8V voltages and the EVB peripherals 1.8V voltages.
JP23	3.0V	FITTED (D)	Connects the MCU 3.0V voltages and the EVB peripherals 3.0V voltages.
JP24	1.2V	FITTED (D)	Connects the MCU 1.2V voltages.
JP25	0.9V~1.2V	FITTED (D)	Connects the MCU 0.9V~1.2V Core voltages.
JP19		REMOVED (D)	0.9V~1.2V core voltage regulator output is set by the signal HIGHCORE. 1.2V for HIGHCORE = LOW; 0.9V for HIGHCORE = HIGH.
JP34	FIXED MODE	REMOVED (D)	1.2V (for HIGHCORE = LOW) is configured as 1.17V~1.31V variable mode controlled by the potentiometer R89.
JP26	1.2V	FITTED (D)	Connects the MCU 1.2V RTC voltages.
JP21		REMOVED (D)	1.2V RTC voltage regulator output is set to 1.2V.
JP20	RTC EXT 5.0V	FITTED (D)	1.2V RTC voltage regulator input is connected to the power supply input connector J17.
JP27	RTC EXT BIAS	1-2 (D)	When JP20 is fitted.
JP32	BOOT SEL	1-2 (D)	GPI_01(SERVICE_N) is set to HIGH to run code from NAND FLASH.

Table 2-18 EVB (Main Board) Default Jumpers Summary Table (cont.)

Jumper	PCB Legend	Position	Description
JP2		FITTED (D)	Connects U2_TX to MAXIM MAX3232ECAE device.
JP3		FITTED (D)	Connects U2_RX to MAXIM MAX3232ECAE device.
JP4		FITTED (D)	Connects U2_HRTS to MAXIM MAX3232ECAE device.
JP5		FITTED (D)	Connects U2_HCTS to MAXIM MAX3232ECAE device.
JP12		1-2 (D)	Connects U7_TX to MAXIM MAX3232ECAE device.
JP13		1-2 (D)	Connects U7_RX to MAXIM MAX3232ECAE device.
JP10		FITTED (D)	Connects U7_HRTS to MAXIM MAX3232ECAE device.
JP11		FITTED (D)	Connects U7_HCTS to MAXIM MAX3232ECAE device.
JP6		FITTED (D)	Connects U5_TX to MAXIM MAX3232ECAE device.
JP7		FITTED (D)	Connects U5_RX to MAXIM MAX3232ECAE device.
JP8		REMOVED (D)	Not in use.
JP9		REMOVED (D)	Not in use.
JP1	ADR	FITTED (D)	The I2C-bus address for the NXP ISP1301 is 0101101 (0x2D).
JP30	SCL	1-2 (D)	Connects I2C1_SCL.
JP31	SDA	1-2 (D)	Connects I2C1_SDA.
JP29	WP_N	1-2 (D)	Accepts program or erase operations.
JP28	LOCKPRE	REMOVED (D)	Not using LOCK MECHANISM & POWER-ON AUTO-READ is not supported.
JP33	ADIN1	FITTED (D)	Connects ADIN1 to 0.9V~1.2V Core voltage.

4. Break-Out Headers

This section details the pinout for the break-out headers on the EVB. All of the break-out headers are all 0.05 inch pitch headers (SAMTEC FTR-140-52-G-D-A).

4.1 Break-Out Header (J5)

[Appendix Figure 5](#)

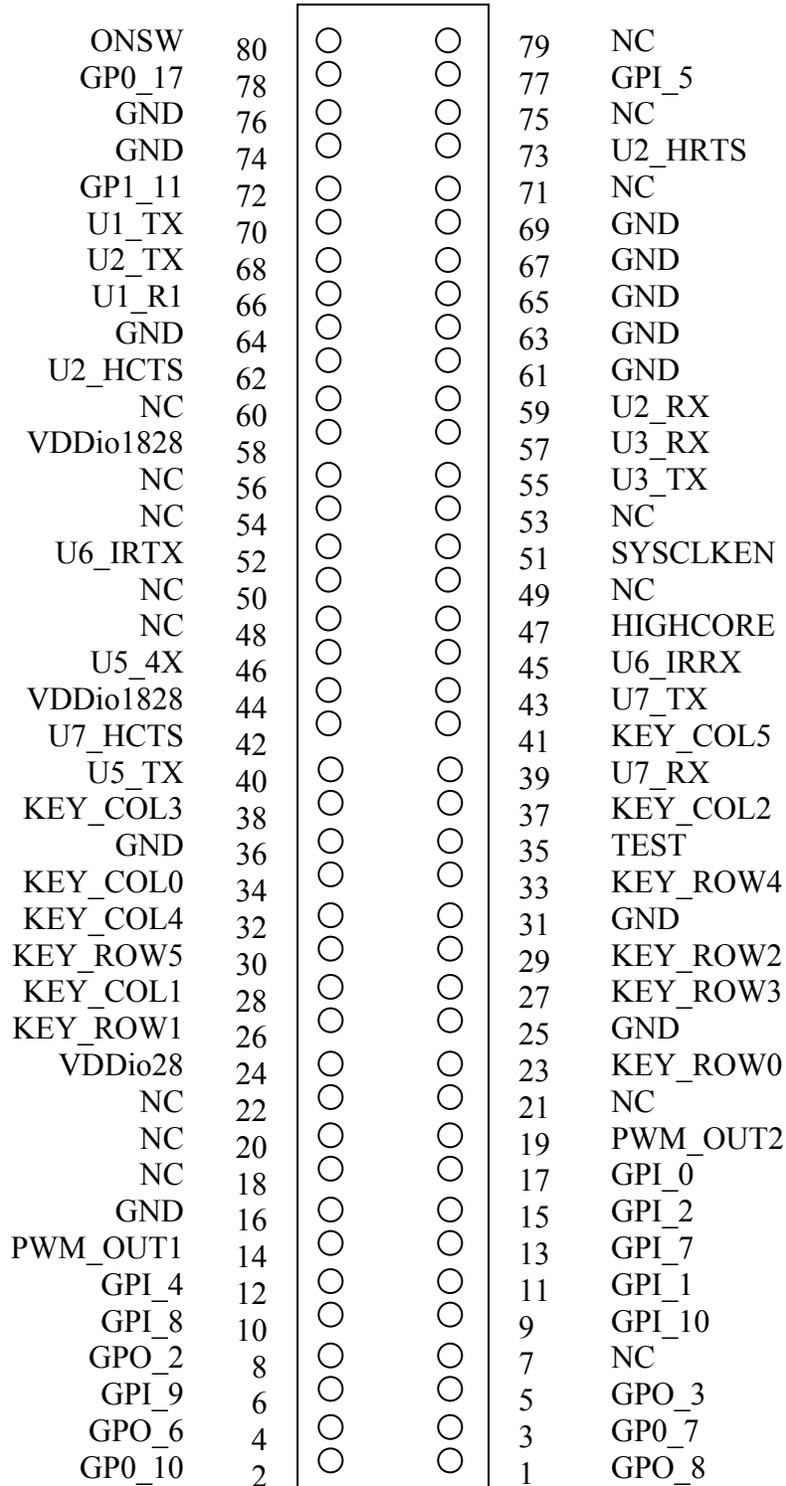


Figure 2-10 Break-Out Header (J5)

4.2 Break-Out Header (J6)

[Appendix Figure 5](#)

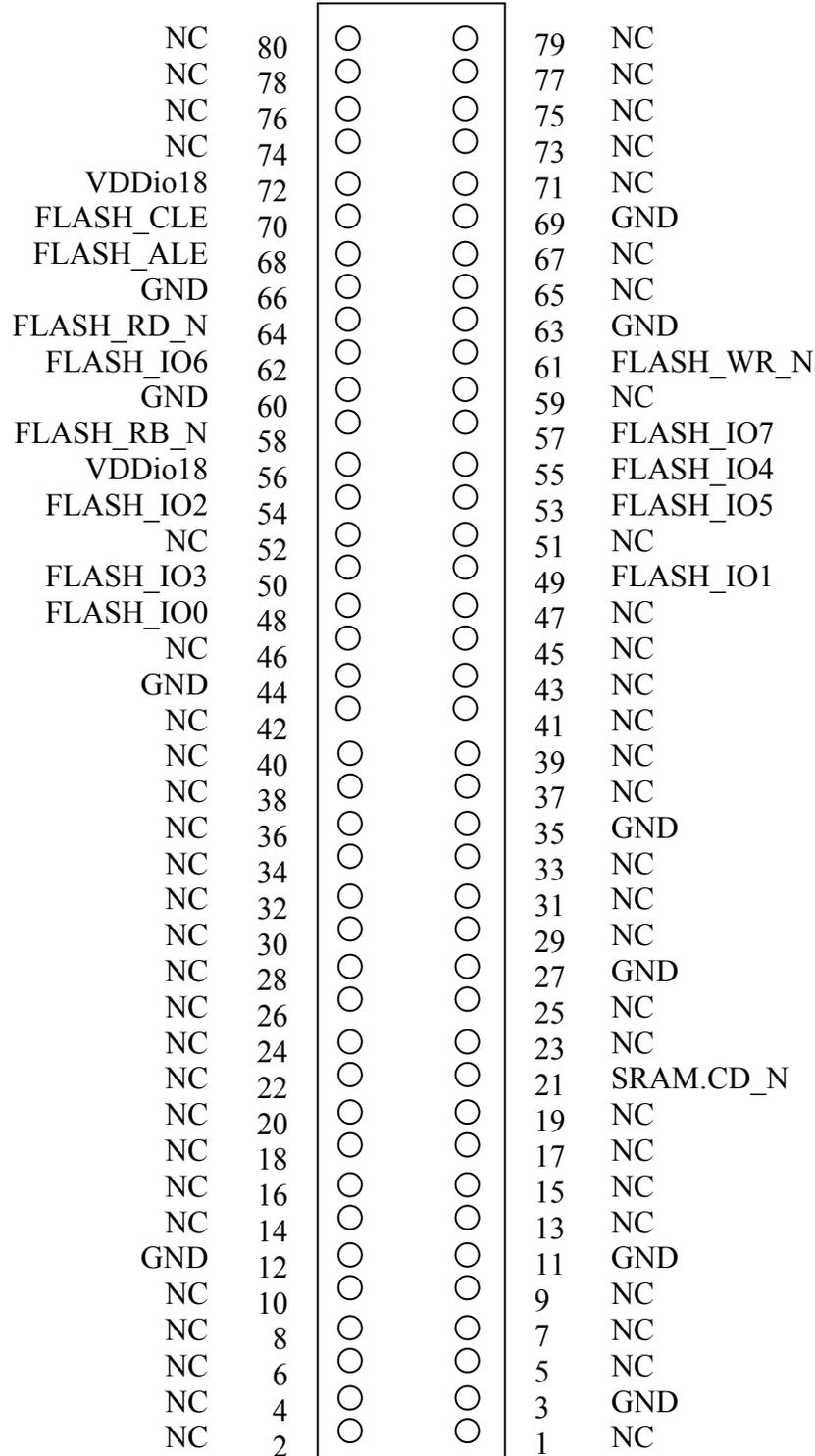


Figure 2-11 Break-Out Header (J6)

4.3 Break-Out Header (J7)

[Appendix Figure 5](#)

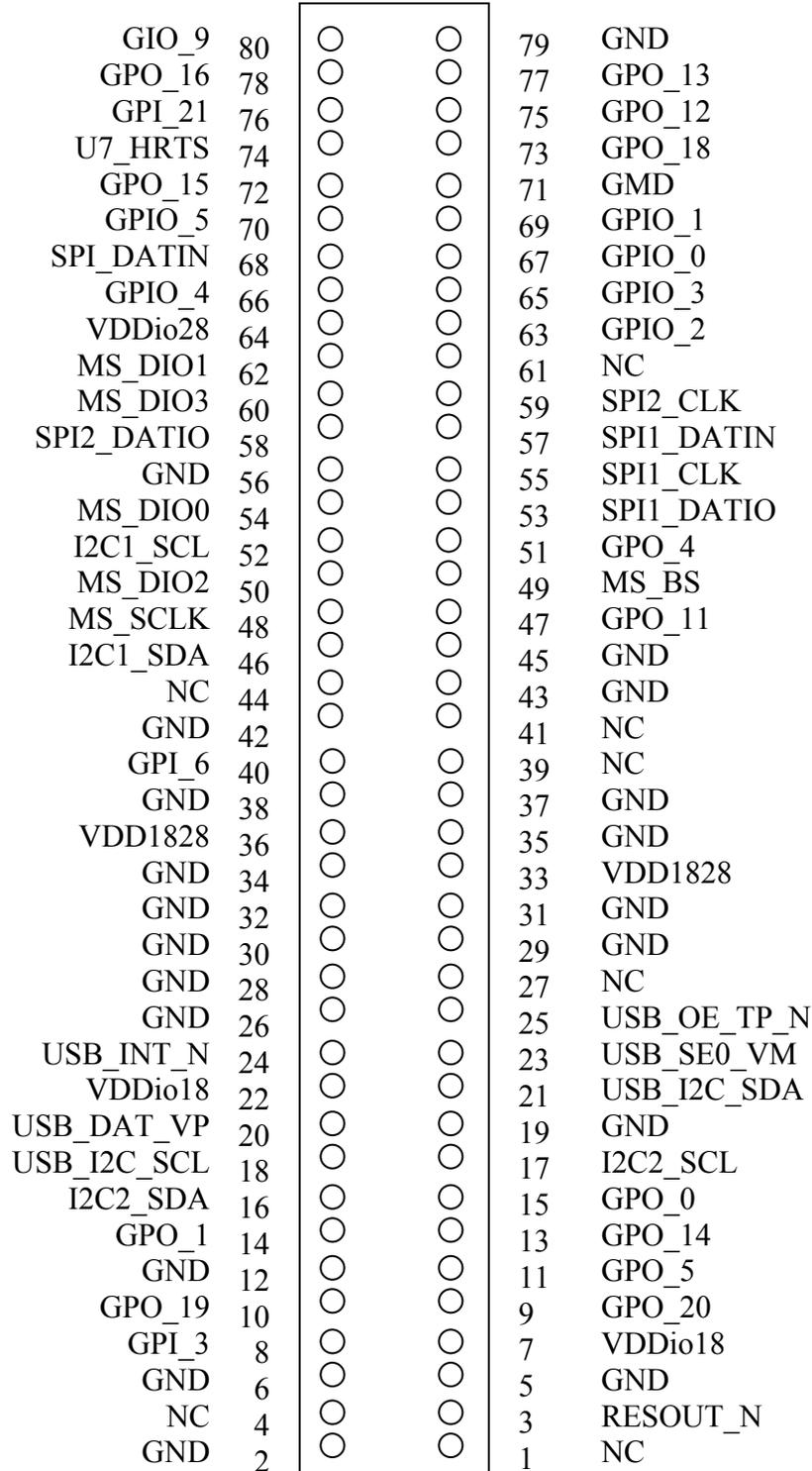


Figure 2-12 Break-Out Header (J7)

4.4 Break-Out Header (J8)

[Appendix Figure 5](#)

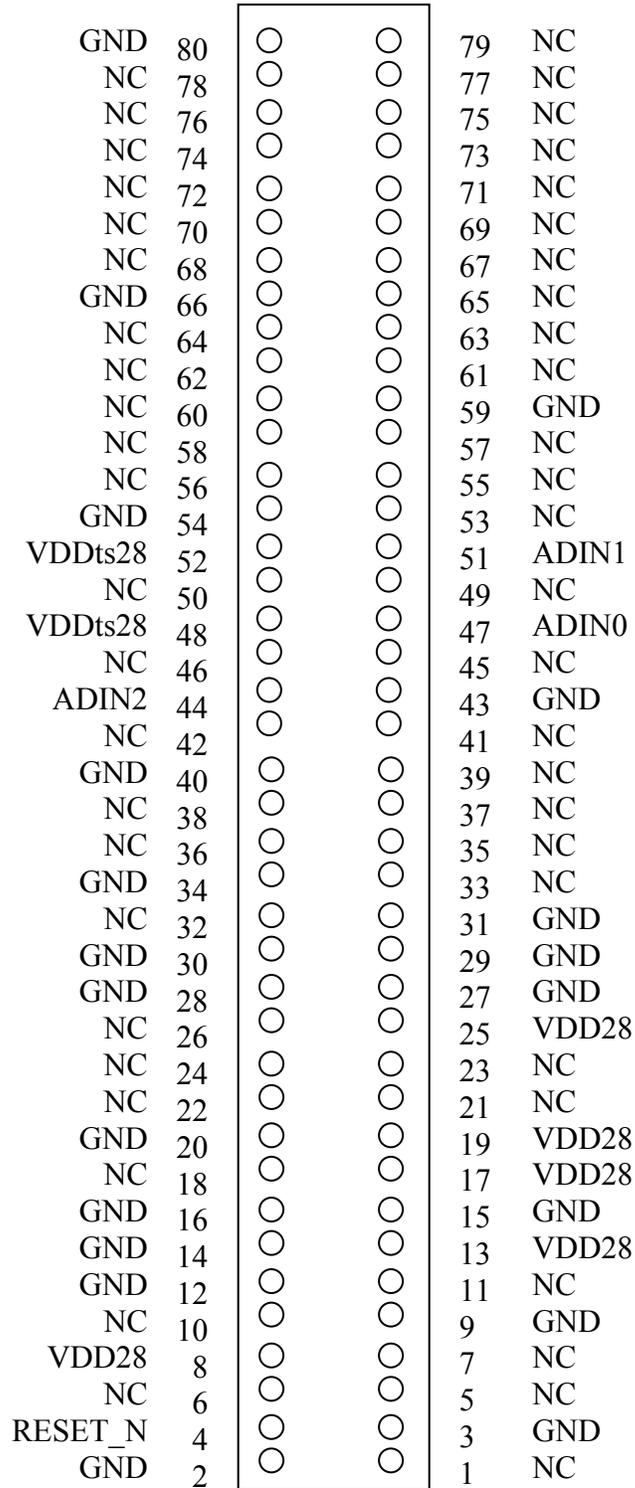


Figure 2-13 Break-Out Header (J8)

5. Seehau Configuration

Installing from the CD

To install the Seehau software, do the following:

1. Insert the Seehau CD into your CD ROM drive. The installation process will start automatically.
2. Click **Install Seehau Interface for EMUL-ARM** and follow the instructions that appear on your screen.

If the installation does not start automatically, you might have your Windows Autorun feature disabled. You will then need to do one of three things:

- Use Windows Explorer and navigate to the CD root directory. Double-click **Autorun.exe**. The Windows Install Shield will start the installation process.
- Right-click on the CD ROM symbol while running Windows Explorer and select **AutoPlay** to start the installation process.
- From the taskbar, select **Start**, then **Settings**. Click on **Control Panel**, then **Add/Remove Programs**, and then **Install**. The installation process will start when you select the correct path to the CD.

Downloading and Installing the Seehau Software From the Internet

1. Go to the ICE Technology web site (<http://www.icetech.com>). Click **Downloads**. The Software Downloads page opens.
2. Click **Current Seehau Software**. The Seehau Software Status page opens.
3. Locate the EMUL-ARM product listing. There will be two listings: one for documentation and one for software.
4. Click **Information and Download (Seehau)**.
5. Review the information on the page.
6. Click **Yes I Want to Download**. A Customer Information Form page opens. Complete this form, then click **Proceed**. (You have the option to download more than one product.) A verification page opens with the information you have just entered. If all information is correct, select **SEND** at the bottom of the page. A message will open that verifies your information has been sent.
7. Click **Go to Download**. The **Available Download Areas** page opens.
8. Click either option for a download site. The Software Updates page opens.
9. Click the EMUL-ARM link.

10. Click the ARM.exe link. The application will start downloading. Make a note of the directory for this downloaded file.
11. Following the download, go to the directory which has the downloaded file. Click the ARM.exe file and follow the installation instructions.

After installing the Seehau software, the **Setup Complete** dialog box appears, allowing you to view the Readme.txt file and/or launch the SeehauARM configuration.

Note

You must launch the SeehauARM configuration before running the Seehau software.

Seehau Configuration Program

After installing Seehau, it is recommended that you automatically start the Seehau Configuration program. Do the following steps before starting Seehau:

1. From the **Setup Complete** dialog box, select **Launch SeehauARM Configuration**.
2. Click **Finish**.

If you do not choose to automatically start the Seehau Configuration Program, do the following:

From the **Start** menu, select **Programs**.

Select **SeehauARM**, then click **Config** to open the **Emulator Configuration** window displaying the **Connect** tab (Figure 2-14). Please note that it is not necessary to be connected at this time.

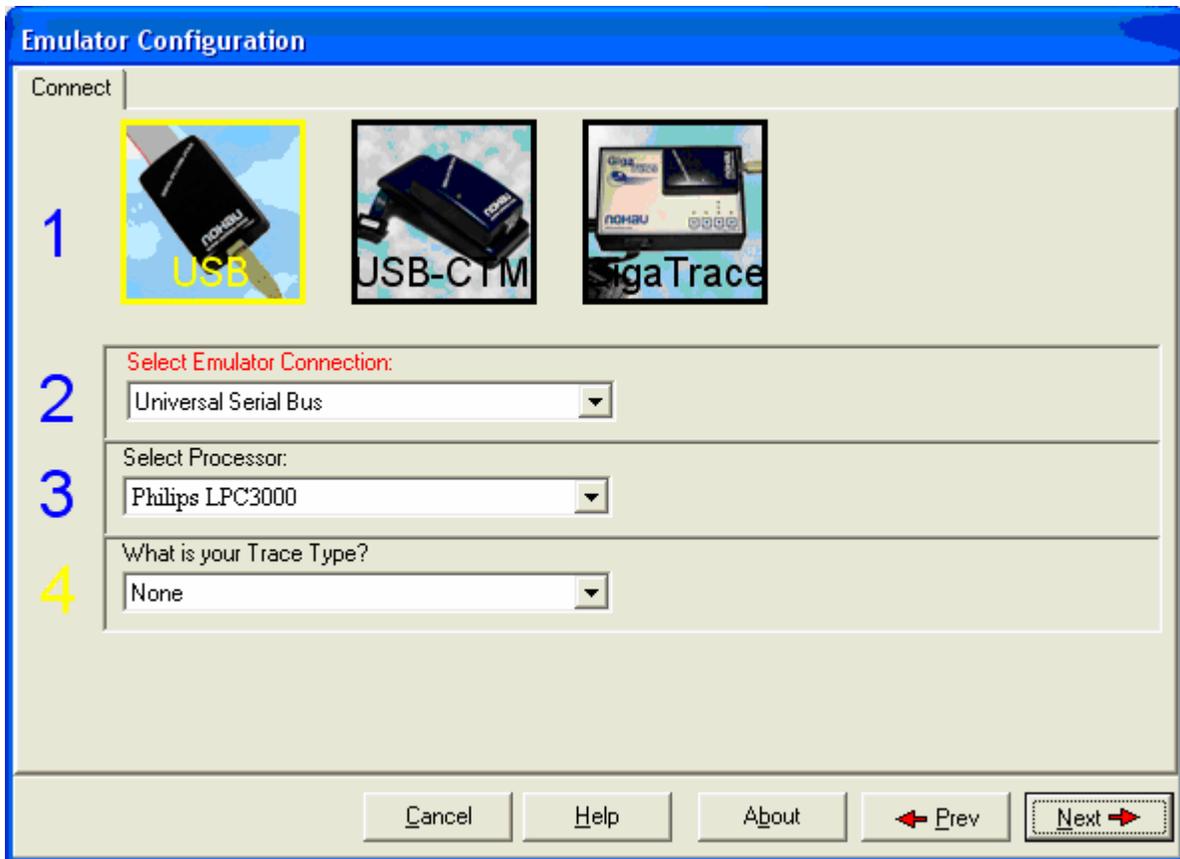


Figure 2-14: Emulator Configuration Window Displaying the Connect Tab

Configuring the Communications Interface Connect Tab

The graphical user interface for this tab is divided into four regions:

1. Region 1 – Communications Interface:

Displays the three communications interface options for the ARM. The USB is for the pod only. If you have the optional Compact Trace Module (CTM), choose the USB-CTM (in the middle). The third box is for the GigaTrace option.

2. Region 2 – Select Emulator Connection:

No action required. Default is **Universal Serial Bus**.

3. Region 3 – Select Processor:

Default is **ARM7 (generic)**. Click on the arrow to view the drop down list for the other devices. For **ARM9**, select **ARM9 (generic)**.

4. Region 4 – What is your Trace Type?:

The default is **Yes** if trace is supported (based on earlier selections).

5. Click Next. The **Hdw Config** tab opens (Figure 2-15).

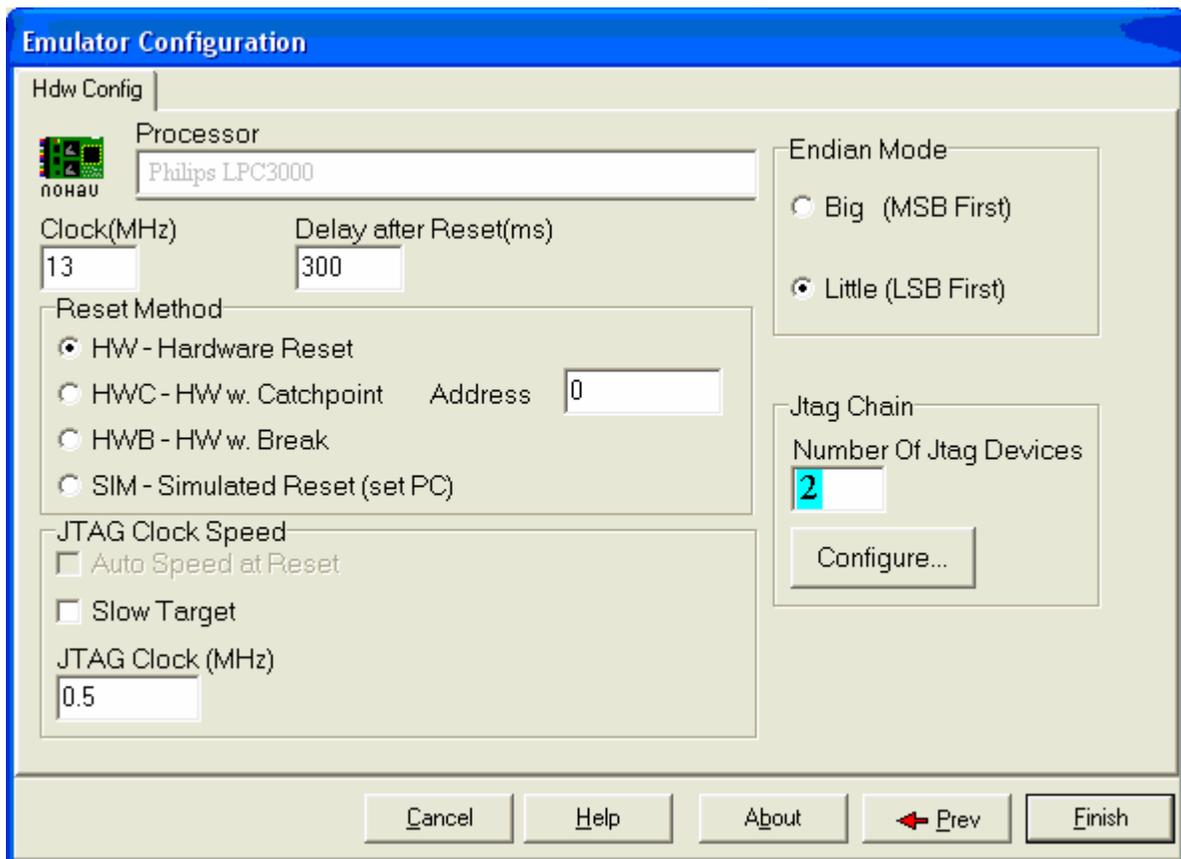


Figure 2-15: Emulator Configuration Window Displaying the Hdw Config Tab

Hardware Configuration Tab

The initial configuration settings are read from the Startup.bas file when the debugger initializes.

After the initial startup and configuration of Seehau, the configuration parameters are saved in the Startup.bas file (located in the Macro subdirectory). The next time the emulator is started, the configuration parameters are read from the Startup.bas file and compared with the default parameters on the chip.

- **Processor:**
Shown for reference only. This is the selected processor. If you need to change the processor, click **Prev**.
- **Clock(MHz):**
This is used for the trace timestamp only. Enables you to set the clock speed.
- **Delay after Reset (ms):**
Used to set the time to wait after reset before accessing the hardware. This allows the target to complete reset operations such as loading the logic into an FPGA.
- **Remap:**
This is used in the ARM chip for remapping the starting address of RAM. When this is selected, the remap bit will be set at reset. On devices that do not provide this, it is not set and will therefore be grayed out.
- **Reset Method**
 - **HW – Hardware Reset:**
Sets a hardware break at address 0 and asserts reset.
 - **HWC – HW w Catchpoint:**
Inserts a jump to itself at the address specified.
 - **HWB – HW wBreak:**
This reset method asserts reset, waits for the set time as determined by the Delay after Reset, then stops execution.
 - **SIM – Simulated Reset (set PC):**
This reset method sets the Program Counter to 0 and does not assert hardware reset.

Note

For a more detailed description of the Reset Method, refer to the Reset Method document called ARM_Reset located in the document folder.

- **JTAG Clock Speed**
 - **Auto Speed at Reset:**
Allows EMUL-ARM to bring the target up to full speed automatically. Not implemented for all MCUs.
 - **Slow Target:**
A special slow target communication mode is entered. Do not use this unless really necessary, since it will slow down target communication significantly. This does not affect the JTAG clock.

- **JTAG Clock (KHz):**
Sets the JTAG clock speed.
- **Endian Mode:** This is used to configure the endianness -- byte ordering -- for your chip.
 - **Big (MSB First):**
Select this if your target has the Most Significant Byte (MSB) first.
 - **Little (LSB First):**
Select this if your target has the Least Significant Byte (LSB) first.

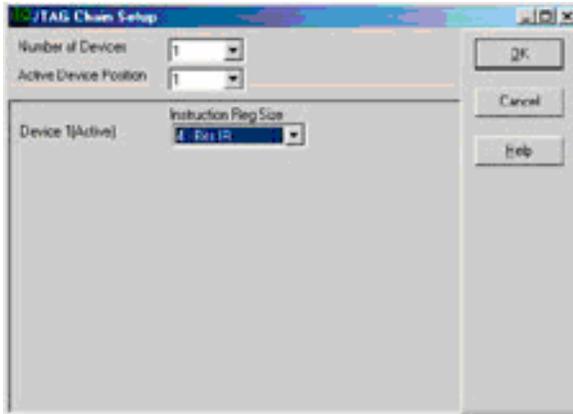


Figure 2-16: JTAG Chain Setup Screen.

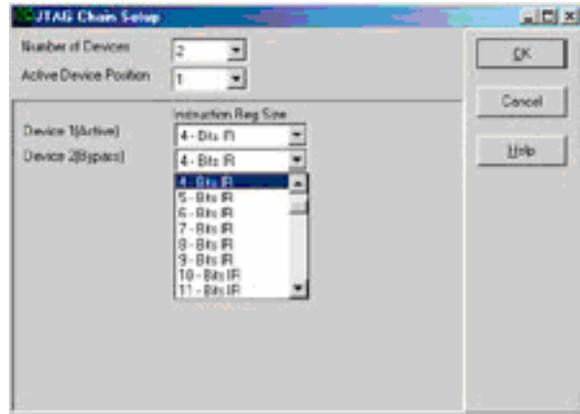


Figure 2-17: Setup Screen with Two Devices

- **JTAG Chain** configuration is used if the ARM device is not the only chip connected to the JTAG, or if the chip has multiple JTAG controllers (Figure 2-16).
 - **Number of JTAG devices:**
This is the total number of devices connected to the JTAG Scan Chain. If only one device is present, nothing needs to be configured.
 - **Configure:**
This button is used to configure the number of devices and the Instruction Length for each device. This is only available during the initial configuration. If you click the **Configure** button, Figure 2-16 or Figure 2-17 appears depending on the number of devices that were entered.
 - **Number of Devices:**
This is used to set the total number of devices in the JTAG Scan Chain (Figure 2-17).
 - **Active Device Position:**
This is used to set which device in the ARM chip the JTAG will connect to.
- **Instruction Reg Size:** There will be a drop down list for each of the devices. If the number of devices is set to more than one, there will be a drop down list for each device (Figure 2-17).
 - **Device1 (Active):**
The Instruction Register size for the active device, which is automatically configured. (ARM7 = 4, ARM9 = 5)

— **Device2(Bypass):**

This is where the Instruction Register Length is set for the device in the chain that will be bypassed.

Configuring the Emulator Options From Within Seehau

In Seehau, open the Emulator Configuration window. From the **Config** menu select **Emulator**. The Emulator Configuration window opens displaying the **Hdw Config** tab (Figure 2-18).

Only the differences from the initial configuration will be discussed here.

The **Emulator Configuration** window contains three tabs. When selected, each tab allows you to set the following options:

Hdw Cfg: Set up emulator hardware options.

Misc Setup: Select reset options.

Map Config Used to manually set the address ranges where Thumb code is stored.

Buttons Common to All Tabs

- **OK:** Saves the settings for the tab and exits the dialog box.
- **Apply:** Saves the settings for the tab.
- **Cancel:** Exits without saving the settings for the dialog box.
- **Help:** Displays the Seehau Help file.
- **Refresh:** Allows you to retrieve and view the current emulator hardware configuration settings.

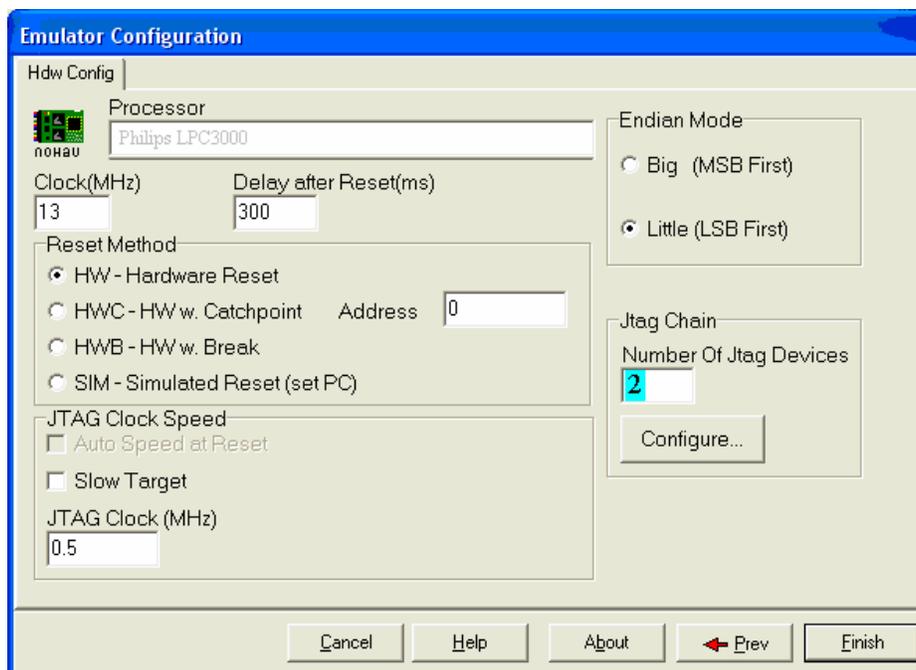


Figure 2-18: Emulator Configuration Window Displaying the Hdw Config Tab

Hardware Configuration Tab

- **JTAG Chain**
 - The **View** button is used to check the current configuration. The configuration can only be changed during the initial configuration.

Miscellaneous Setup Tab

The **Misc Setup** tab (Figure 2-19) is accessible only after the initial software configuration.

- **Reset chip after load file:**
 - Sets the ARM core to issue a reset after the code is loaded.
- **Override at Reset**
 - The **Program Counter** option selects the value that the program counter will be set to after the reset sequence has completed. Enter the program counter value in the box.
 - The **Stack Pointer** option selects the value that the stack pointer will be set to after a reset. Enter the stack pointer value in the box.

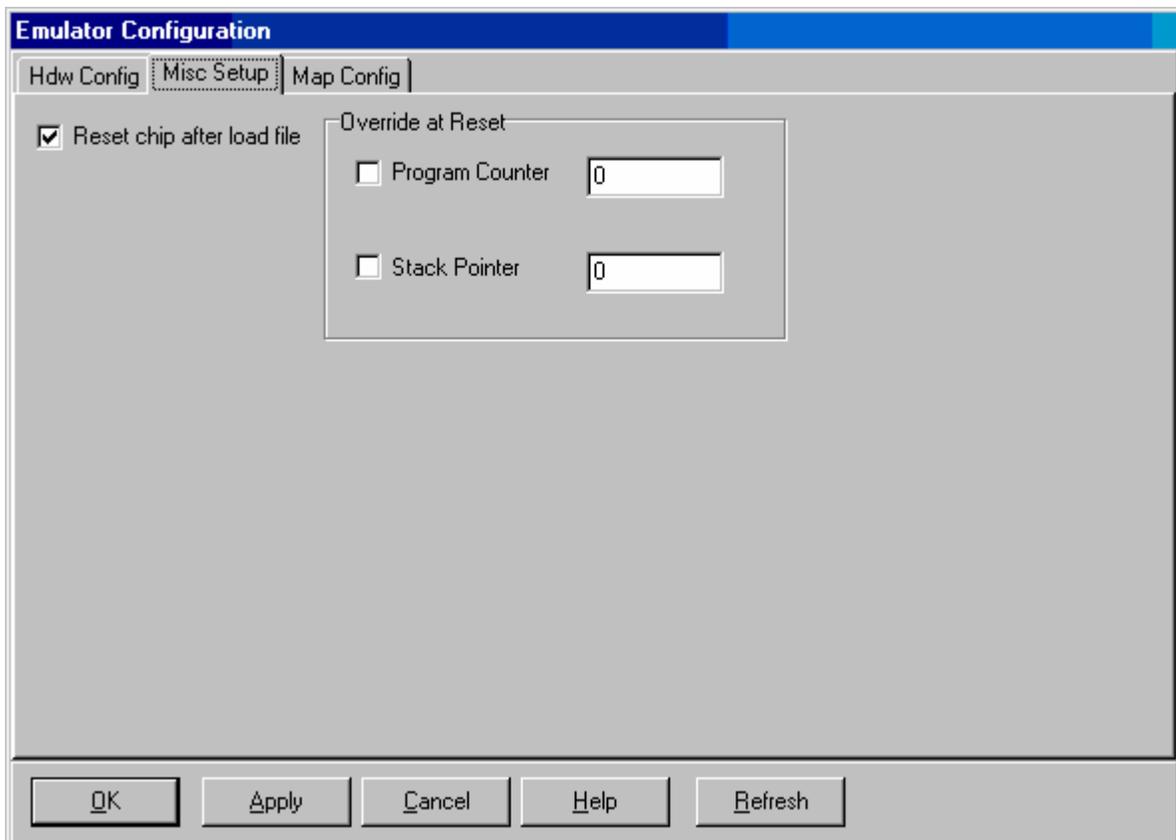


Figure 2-19: Emulator Configuration Window Displaying the Misc Setup Tab

Map Config TAB

Figure 2-20 is accessible only after the initial software configuration. The file loader will automatically map THUMB regions defined in the output file. This mapping window provides a manual override for THUMB regions. The large open area displays the address ranges that contain THUMB code.

- The **Add** button is used to add a range of memory that is used for THUMB code.
- The **Edit** button is available only when a range is selected. The range values may be changed.
- The **Remove** button is used to delete one memory range from the table.
- The **Remove All** button is used to delete all the memory ranges from the table.

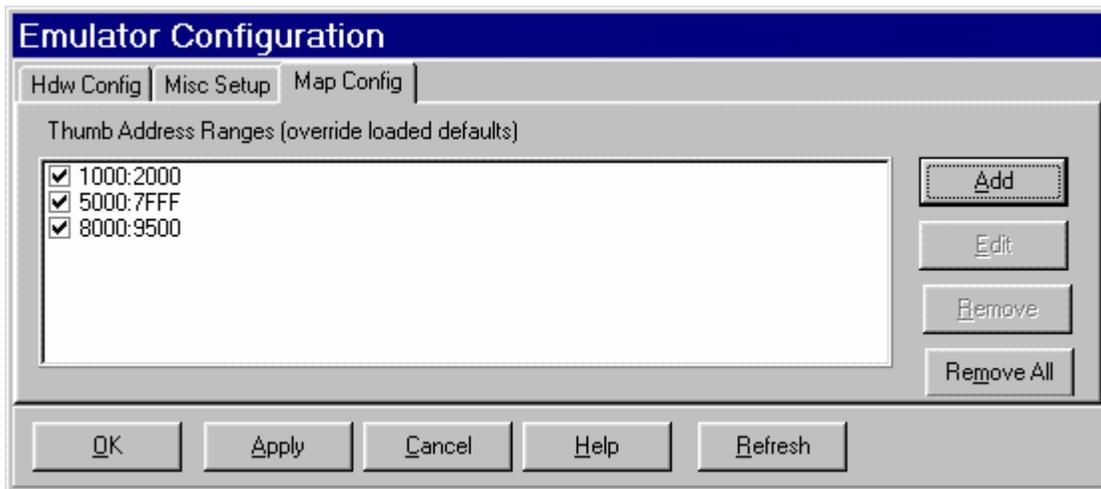


Figure 2-20: Emulator Configuration Window Displaying the Map Config Tab

6. NAND Flash Programming

There is a button on the tool bar to start the NANDFlash Programming macro.



6.1 NAND Flash Programming Main Dialog Box

When you press this button the following screen should appear (figure 2-21)

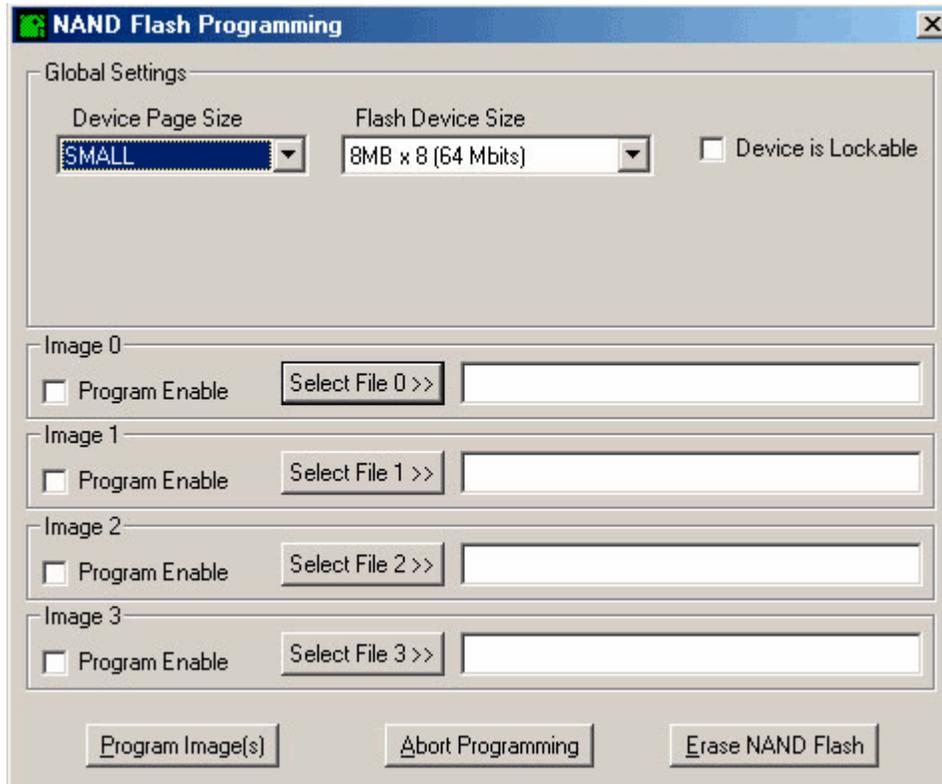


Figure 2-21 NAND Flash Programming Main Dialog

<u>Field</u>	<u>Description</u>
Device Page Size	<p>The Page Size of the NAND Flash device is either Small or Large. For Small Page device, the Page Size is 528 Byte (x8 bus width) / 264 Word (x16 bus width).</p> <p>For Large Page device, the Page Size is 2112 Byte (x8 bus width) / 1056 Word (x16 bus width).</p> <p>For Small Page device, three bus cycles are required to input the addresses for devices having 256Mbit or less; four bus cycles are required to input the addresses for devices having 512Mbit or more. For Large Page device, four bus cycles are required to input the addresses for devices having 1Gbit or less; five bus cycles are required to input the addresses for devices having 2Gbit or more.</p>

The NAND Flash device in the NXP LPC3000 Evaluation Board is STMicroelectronics NAND256R3A which is a Small Page device.

Flash Device Size	<p>The NXP LPC3000 supports x8 bus width only. The NAND Flash devices supported by the NSeeHauARM NAND Flash Programming Utility are 8MByte x 8 (64 Mbit), 16MByte x 8 (128 Mbit), 32MByte x 8 (256 Mbit), 64MByte x 8 (512 Mbit), 128MByte x 8 (1 Gbit), 256MByte x 8 (2 Gbit), 512MByte x 8 (4 Gbit), 1GByte x 8 (8 Gbit), 2GB x 8 (16 Gbit).</p>
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The NAND Flash device in the NXP LPC3000 Evaluation Board is STMicroelectronics NAND256R3A which is a 32MByte x 8 (256 Mbit) device.

Device is Lockable	<p>Most NAND Flash devices feature a Write Protect, /WP, pin, which can be used to protect the device against program and erase operations.</p> <p>Additionally, some NAND Flash devices feature a Block Lock mode, which is enabled by setting the Power-Up Read Enable, Lock/Unlock Enable, PRL, pin to High. The Block Lock mode has two levels of software protection - Blocks Lock/Unlock and Blocks Lock-down.</p>
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The NAND Flash device in the NXP LPC3000 Evaluation Board is STMicroelectronics NAND256R3A which does not support the Block Lock mode.

Program Enable	<p>If this option is checked it will enable any or all of the four program Image files to be programmed into the memory during the Programming process.</p>
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When you click on this option, if it is not checked, it will open another dialog screen for additional settings. (Figure 2-22)

****Note****

If checked, you will need to click if off then on to review the settings.

Select File buttons

If the Image File to Load is a Secondary Boot Loader, then it is simply a binary image. The SeehauARM NAND Flash Programming Utility will automatically generate necessary the Interface Configuration Data.

The only Image File Option that can be used for the Secondary Boot loader is **Image 0**.

6.2 NAND Flash Image Options Dialog Box

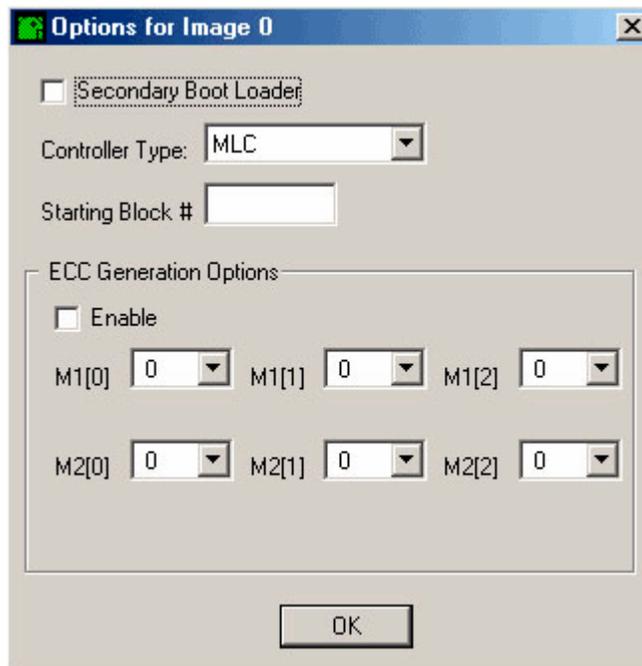


Figure 2-22 NAND Flash Image Options

<u>Field</u>	<u>Description</u>
Secondary Boot Loader	<p>In the NXP LPC3000, there is a built in ROM of 16KB which contains code to start running code from NAND FLASH or to download code from UART to IRAM if in service mode. After reset, execution begins from internal ROM. The program in the ROM is called the Boot Code. The Boot Code SW first reads input GPIO_01 (SERVICE_N). If GPIO_01 is high, the Boot Code starts NAND FLASH booting. The image in the NAND Flash device which is access by the Boot Code is referred as the Secondary Boot Loader. For the flash boot procedure to work it need to find the information (Interface Configuration Data) for, how many page to copy and the type of flash that is connected. The first page in the first block or the second block of the flash shall contain the information (Interface Configuration Data) needed for the flash boot code to work. If the Secondary Boot Loader checkbox is checked, the Seehau ARM NAND Flash Programming Utility will automatically generate the Interface Configuration Data. The Secondary Boot Loader is simply a binary image which does not contain the Interface Configuration Data.</p>

Controller Type	<p>The NXP LPC3000 has two NAND Flash Controllers, one (MLC) for multi level NAND Flash devices and one (SLC) for single level NAND Flash devices. The two NAND Flash Controllers use the same interface to the external NAND Flash device.</p>
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Starting Block #	<p>It specifies the starting block position for the image to be programmed into the NAND Flash device.</p>
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The NAND Flash devices are supplied with all the locations inside valid blocks erased (FFh). The Bad Block Information is written prior to shipping. The Seehau ARM NAND Flash Programming Utility uses Skip Block Method in the Bad Block Management. In the Skip Block method the algorithm creates the Bad Block Table and when the target address corresponds to a Bad Block address, the data is stored in the next good block, skipping the Bad Block. During the lifetime of the NAND device additional Bad Blocks may develop. When a Bad Block is generated during the lifetime of the NAND Flash device, it's data is also stored in the next good block. In this case, the information that indicates which good block corresponds to each developed Bad Block, also has to be stored in the NAND Flash device.

****Important Note****

If there are multiple images to be program into the device, then, in order to avoid the overlapping of the images because of the Skip

Block Method, the user should keep a reasonable margin when specify the starting block position of the image.

ECC Generation Enable	For MLC, it features HW support for Reed-Salomon Encoding/Decoding (10 bit symbols), capable to correction of 4-symbol (4-40bit), without SW needed. For SLC, it features HW support for ECC (Error Checking and Correction) on main area data. If an error is detected the SW must correct it. The ECC on the spare area must be done in SW.
ECC Generation Locations M10-M22	For SLC, the ECC (3Byte) generation of the main area is done by HW and is based on data blocks of 256Byte.

6.3 NAND Flash Erase

To erase a block or range of blocks in the NAND Flash you can click on the Erase NAND Flash button on the Main Dialog Box. You will then see a screen like what is shown in figure 2.23.

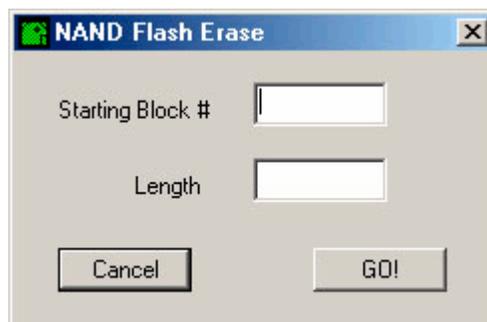
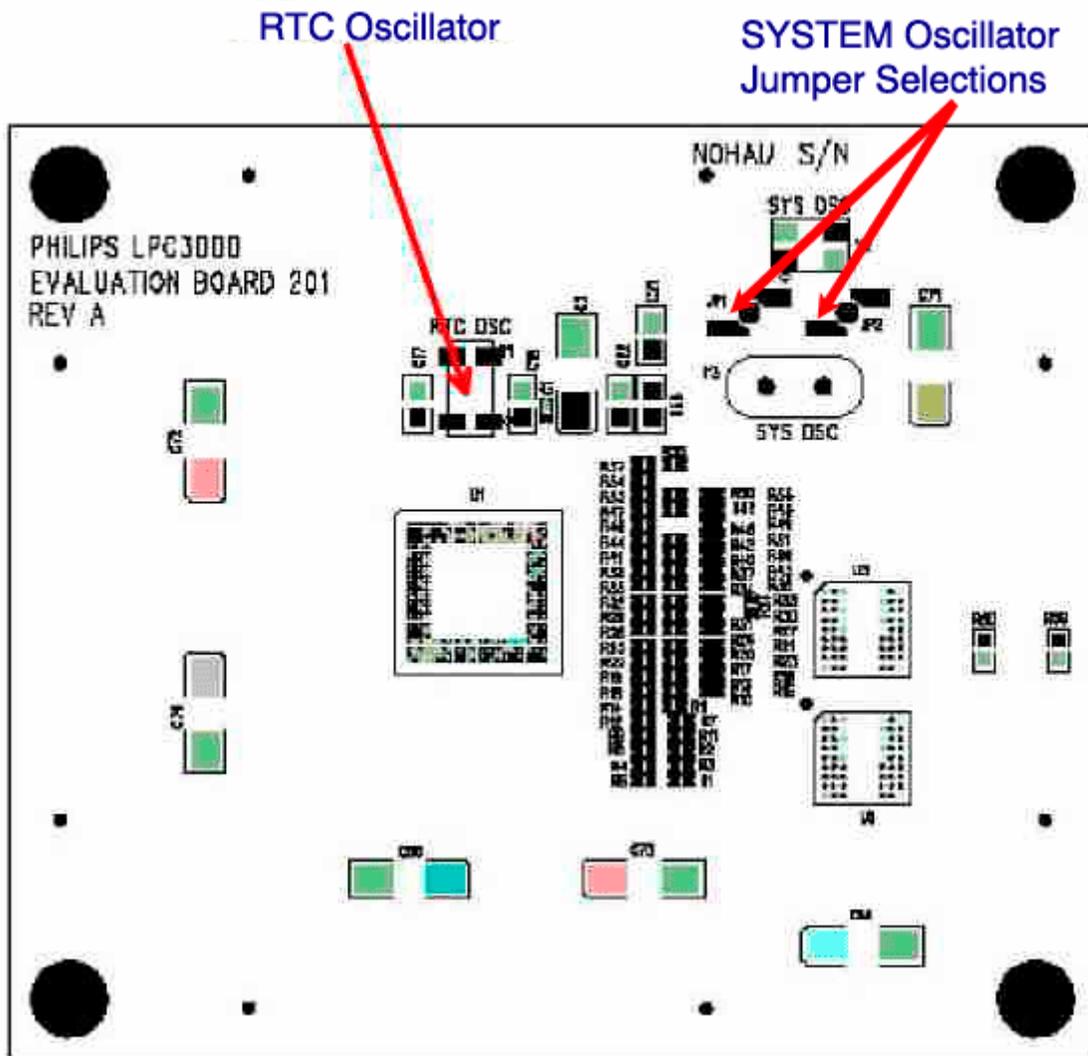
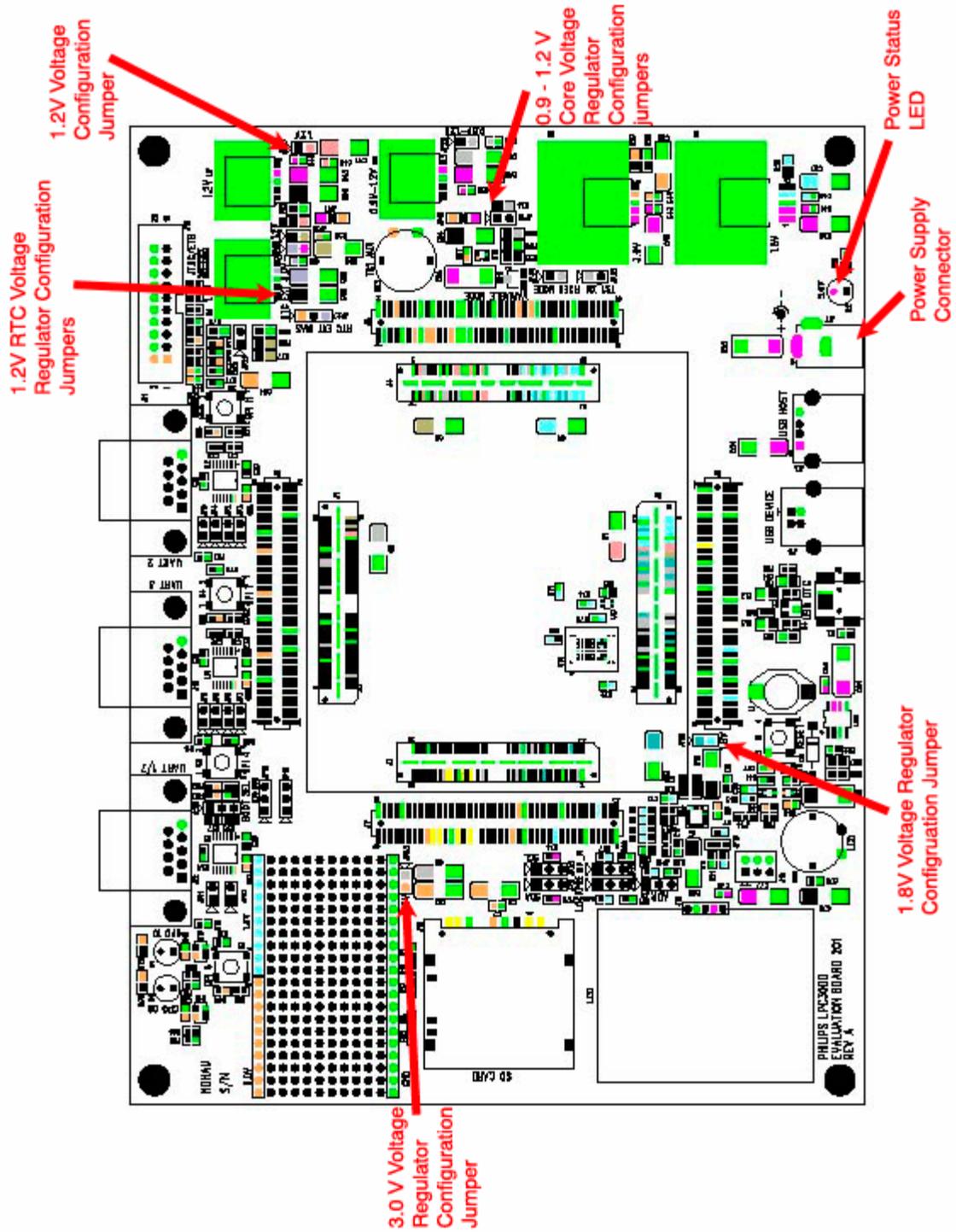


Figure 2-23 NAND Flash Erase Dialog Box

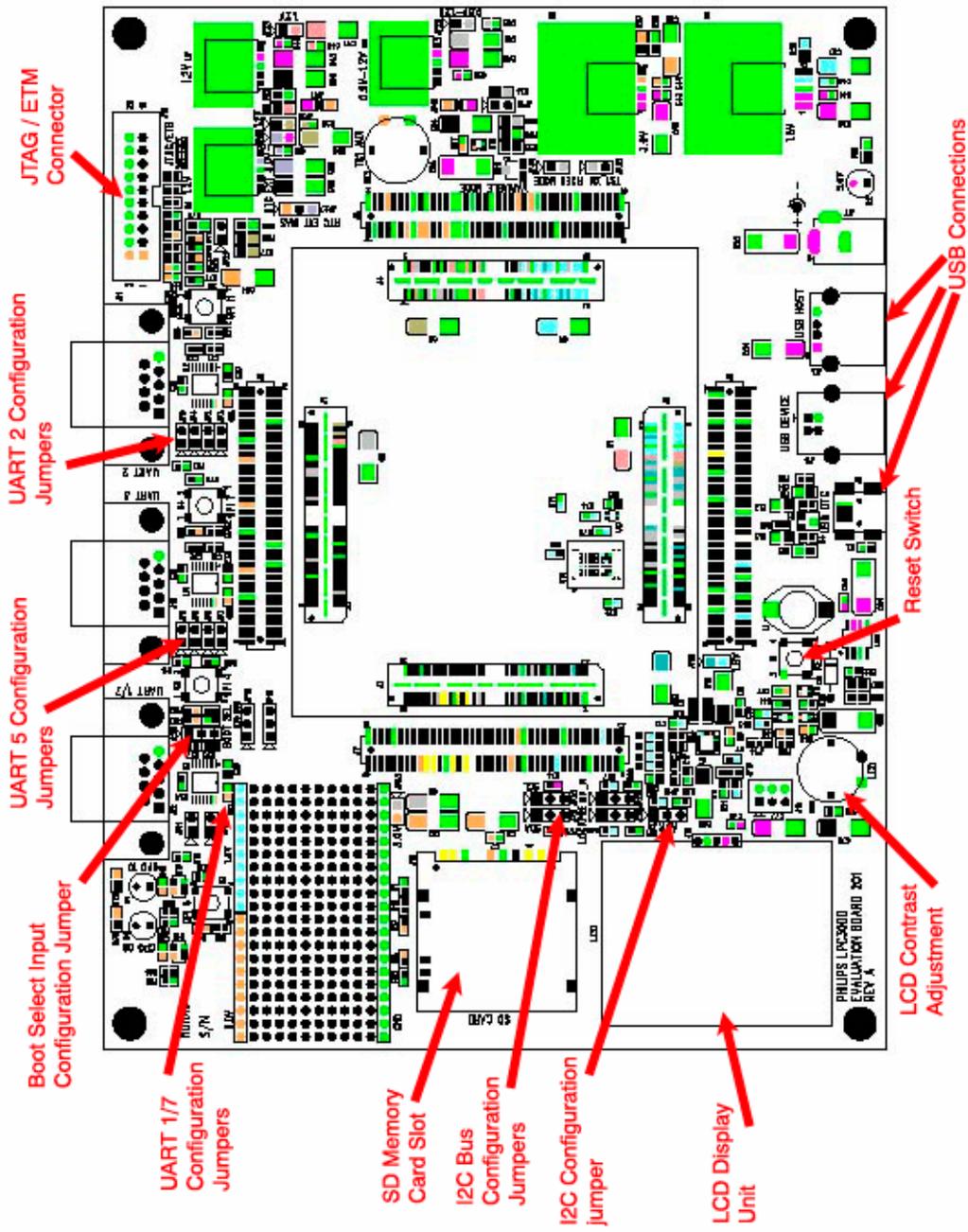
Select the starting block number and a length of blocks to be erased. Enter a 1 for just a single block.



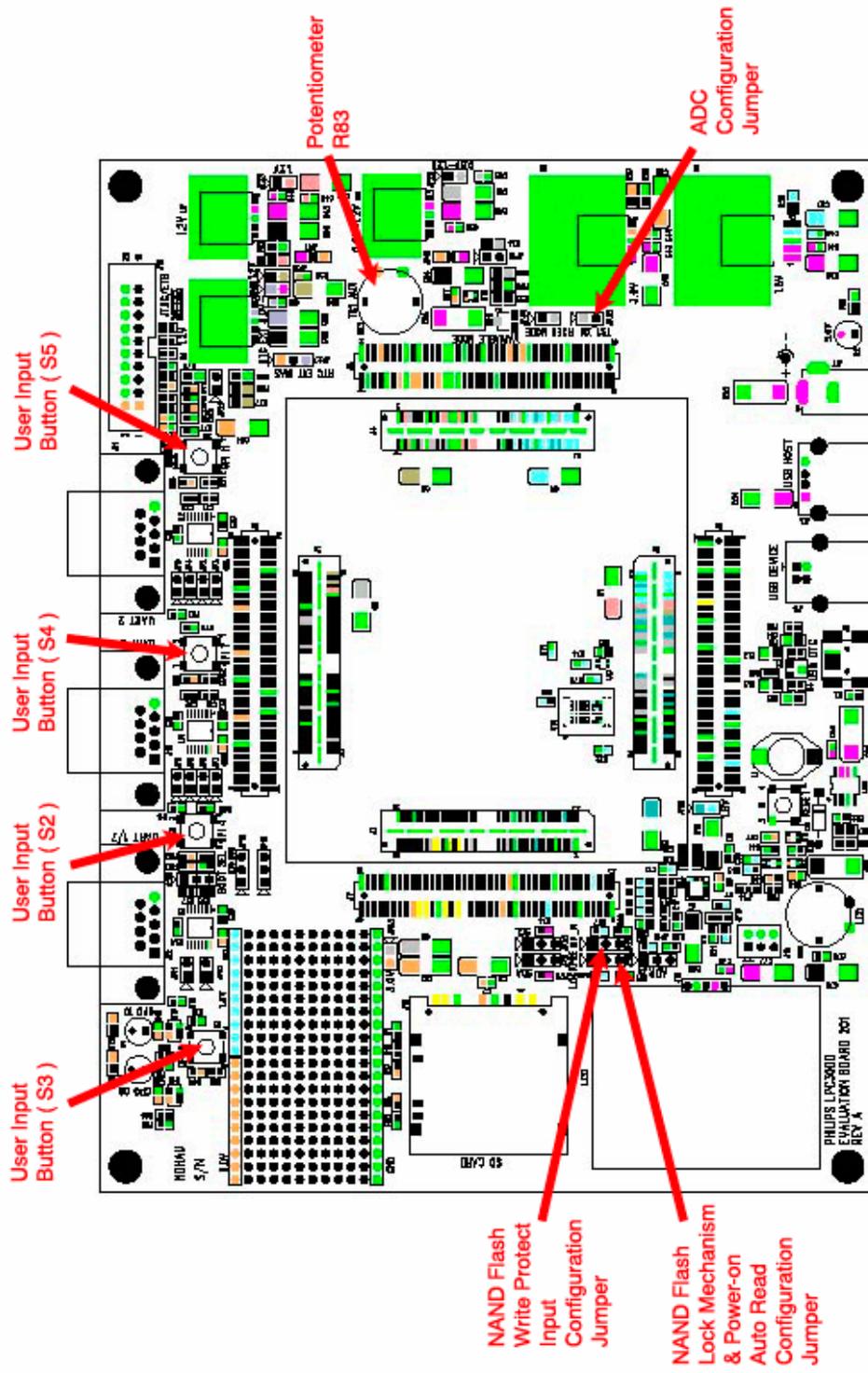
Appendix Figure 1



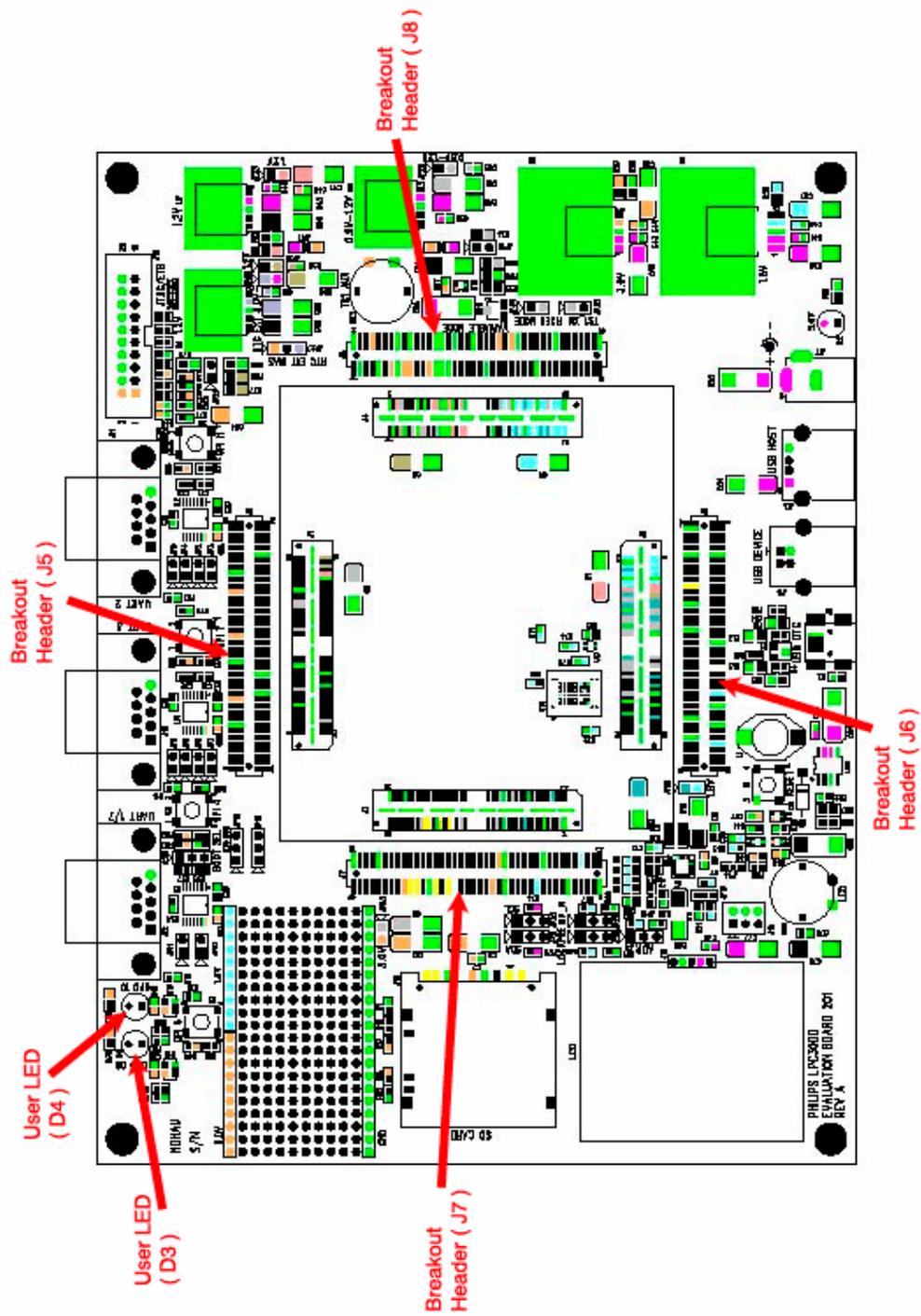
Appendix Figure 2



Appendix Figure 3



Appendix Figure 4



Appendix Figure 5